

R6530KNX3

Nch 650V 30A Power MOSFET

| V _{DSS} | 650V |
|----------------------------|--------|
| R _{DS(on)} (Max.) | 0.140Ω |
| I _D | ±30A |
| P_{D} | 307W |

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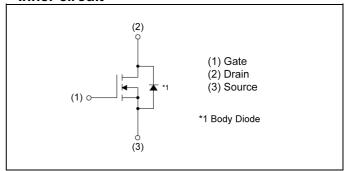
●Outline



Features

- 1) Low on-resistance
- 2) Ultra fast switching
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

•Inner circuit



Application

Switching

Packaging specifications

| Packing | Tube |
|----------------|-----------|
| Packing code | C16 |
| Marking | R6530KNX3 |
| Quantity (pcs) | 1000 |

ullet Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

| Parameter | Symbol | Value | Unit | |
|--|----------------|--------------------|-------------|----|
| Drain - Source voltage | | V _{DSS} | 650 | V |
| Continuous drain current (T _c = 25°C) | | I _D *1 | ±30 | Α |
| Pulsed drain current | | I _{DP} *2 | ±90 | Α |
| static | | V | ±20 | V |
| Gate - Source voltage | AC(f>1Hz) | V_GSS | ±30 | V |
| Avalanche current, single pulse | | I _{AS} | 5.2 | А |
| Avalanche energy, single pulse | | E _{AS} *3 | 730 | mJ |
| Power dissipation (T _c = 25°C) | P _D | 307 | W | |
| Junction temperature | T _j | 150 | °C | |
| Operating junction and storage temper | ature range | T _{stg} | -55 to +150 | °C |

●Thermal resistance

| Downwortow | Cymah al | Values | | | 1.1 |
|--|----------------------|--------|------|------|------|
| Parameter | Symbol | Min. | Тур. | Max. | Unit |
| Thermal resistance, junction - case | R _{thJC} *4 | - | - | 0.41 | °C/W |
| Thermal resistance, junction - ambient | R _{thJA} | - | - | 80 | °C/W |
| Soldering temperature, wavesoldering for 10s | T _{sold} | - | - | 265 | °C |

● Electrical characteristics (T_a = 25°C)

| Darameter | Cumb al | Conditions | Values | | | Unit |
|---|--|---|--------|-------|-------|-------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Offic |
| Drain - Source breakdown voltage | $V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$ | | 650 | - | - | V |
| | | $V_{DS} = 650V, V_{GS} = 0V$ | | | | |
| Zero gate voltage drain current | I _{DSS} | $T_j = 25^{\circ}C$ | - | - | 100 | μΑ |
| aram canoni | | $T_j = 125^{\circ}C$ | - | - | 1000 | |
| Gate - Source leakage current | I _{GSS} | V_{GS} = ±20V, V_{DS} = 0V | 1 | - | ±100 | nA |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_{D} = 960 \mu A$ | 3.0 | - | 5.0 | ٧ |
| | | V _{GS} = 10V, I _D = 14.5A | | | | |
| Static drain - source on - state resistance | R _{DS(on)} *5 | $T_j = 25^{\circ}C$ | - | 0.125 | 0.140 | Ω |
| | | $T_j = 125^{\circ}C$ | - | 0.26 | - | |
| Gate resistance | R_{G} | f = 1MHz, open drain | - | 2.1 | - | Ω |

● Electrical characteristics (T_a = 25°C)

| Darameter | Cymah al | Conditions | Values | | | Unit |
|------------------------------|--------------------------|---------------------------------------|--------|------|------|------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
| Input capacitance | C _{iss} | V _{GS} = 0V | - | 2350 | - | |
| Output capacitance | C _{oss} | V _{DS} = 25V | - | 2200 | - | pF |
| Reverse transfer capacitance | C_{rss} | f = 1MHz | - | 70 | 1 | |
| Turn - on delay time | $t_{d(on)}^{*5}$ | $V_{DD} \simeq 300V$, $V_{GS} = 10V$ | - | 40 | ı | |
| Rise time | t _r *5 | I _D = 15A | - | 90 | 1 | 20 |
| Turn - off delay time | t _{d(off)} *5 | $R_L \simeq 20\Omega$ | - | 100 | - | ns |
| Fall time | t _f *5 | $R_G = 10\Omega$ | - | 55 | - | |

● Gate charge characteristics (T_a = 25°C)

| Daramatar | Currely of | Conditions | Values | | | Linit |
|----------------------|------------------------|--|--------|------|------|-------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
| Total gate charge | Q_g^{*5} | V _{DD} ≈ 300V | - | 56 | - | |
| Gate - Source charge | Q _{gs} *5 | I _D = 30A | - | 18 | - | nC |
| Gate - Drain charge | Q _{gd} *5 | V _{GS} = 10V | - | 22 | - | |
| Gate plateau voltage | V _(plateau) | V _{DD} ≈ 300V, I _D = 30A | - | 6.6 | - | V |

^{*1} Limited only by maximum channel temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \doteqdot 50mH, V_{DD}=50V, R_G=25 Ω , STARTING T_j=25 $^{\circ}$ C

^{*4} T_C=25°C

^{*5} Pulsed

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

| Parameter | Symbol | Conditions | Values | | | Unit |
|-------------------------------|---------------------------|---|--------|------|------|-------|
| - Farameter | Symbol | Conditions | Min. | Тур. | Max. | Offic |
| Source current | I _S *1 | · T _C = 25°C | 1 | - | 30 | Α |
| Pulsed source current | I _{SP} *2 | 1C - 23 C | 1 | - | 90 | Α |
| Source-Drain voltage | V _{SD} *5 | $V_{GS} = 0V, I_{S} = 30A$ | - | - | 1.5 | V |
| Reverse recovery time | t _{rr} *5 | | - | 570 | - | ns |
| Reverse recovery charge | Q _{rr} *5 | I _S = 30A di/dt = 100A/μs | - | 11.4 | - | μC |
| Peak reverse recovery current | _{rr} *5 | | - | 40 | - | Α |

Fig.1 Power Dissipation Derating Curve

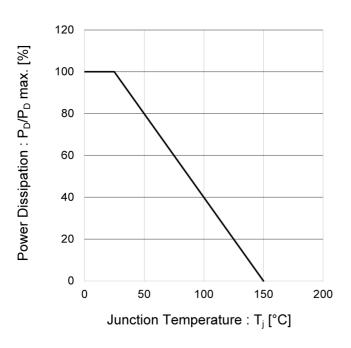


Fig.2 Drain Current Derating
Curve vs. Ambient Temperature

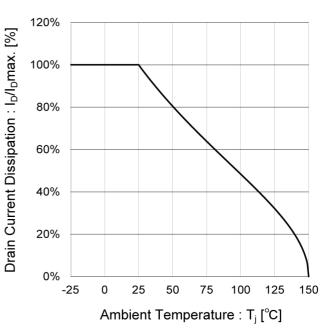


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

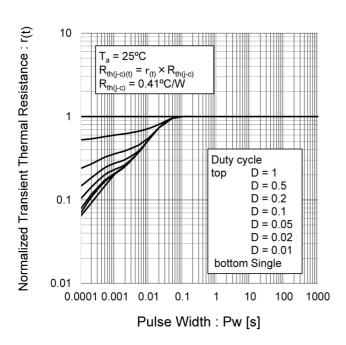


Fig.4 Maximum Safe Operating Area

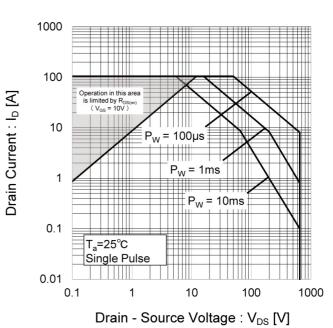


Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

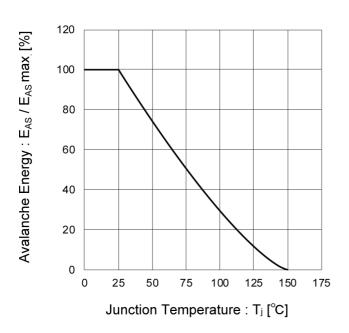


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

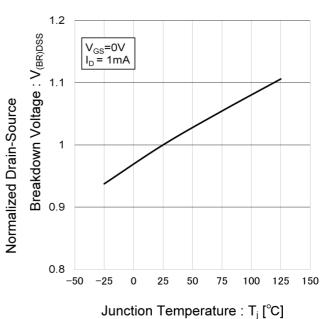


Fig.7 Typical Output Characteristics(I)

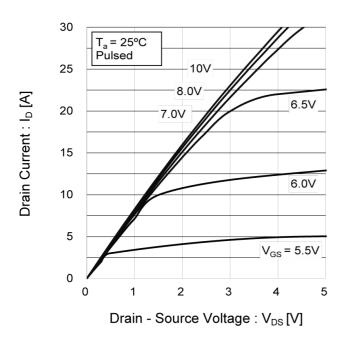
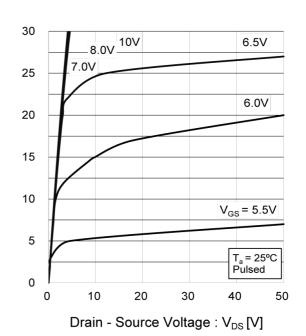


Fig.8 Typical Output Characteristics(II)



Drain Current : I_D [A]

Fig.9 Typical Transfer Characteristics

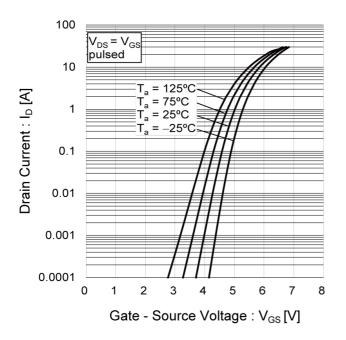


Fig.10 Normalized Gate Threshold .

Voltage vs Junction Temperature

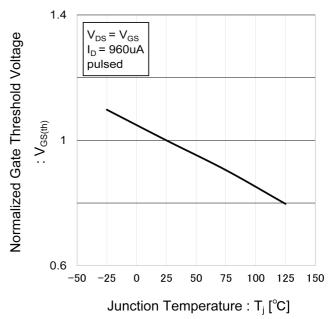


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

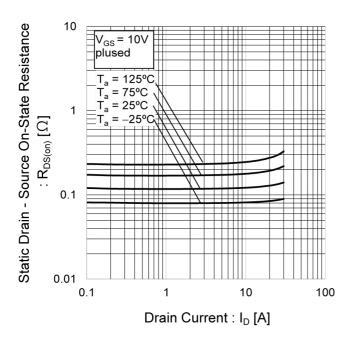


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

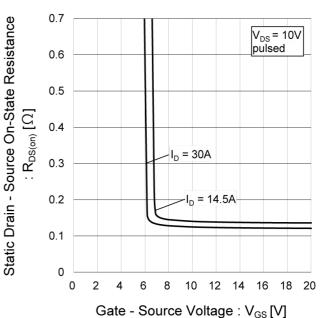


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

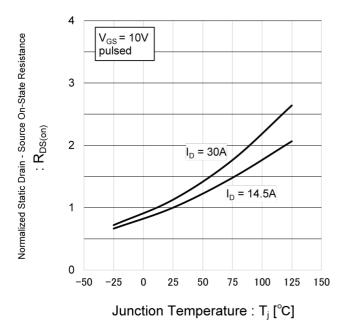


Fig.14 Typical Capacitance vs.

Drain - Source Voltage

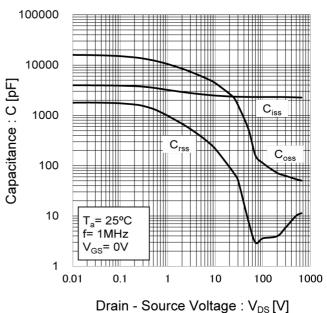


Fig.15 Switching Characteristics

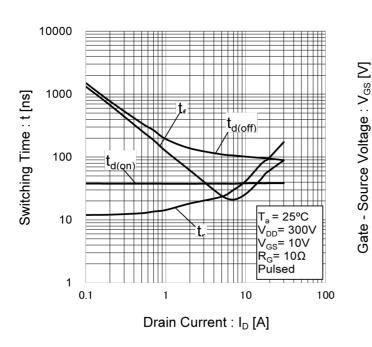


Fig.16 Typical Gate Charge

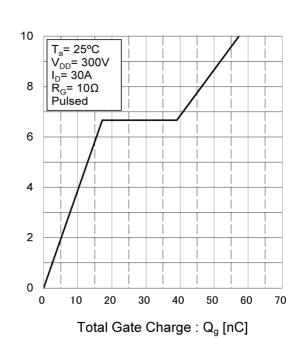


Fig.17 Source Current vs. Source - Drain Voltage

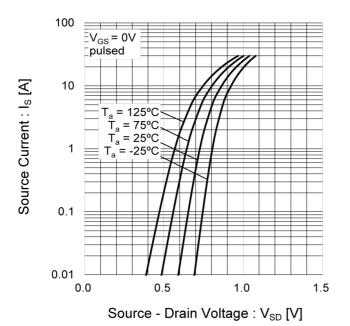
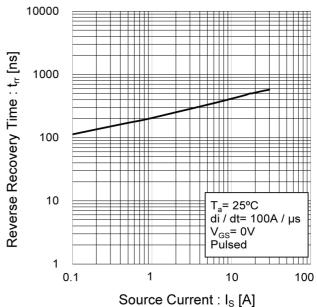


Fig.18 Reverse Recovery Time vs. Source Current



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

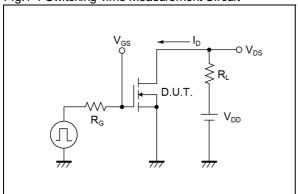


Fig.2-1 Gate Charge Measurement Circuit

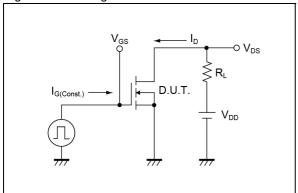


Fig.3-1 Avalanche Measurement Circuit

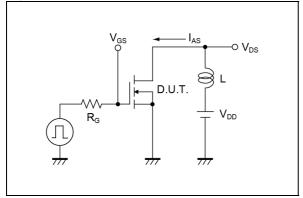


Fig.4-1 trr Measurement Circuit

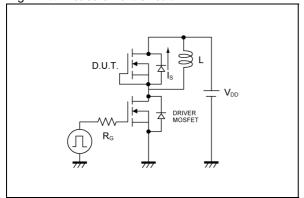


Fig.1-2 Switching Waveforms

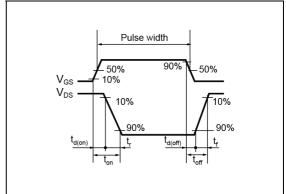


Fig.2-2 Gate Charge Waveform

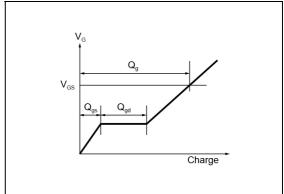


Fig.3-2 Avalanche Waveform

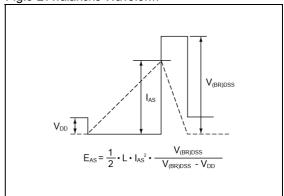
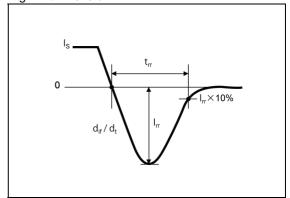
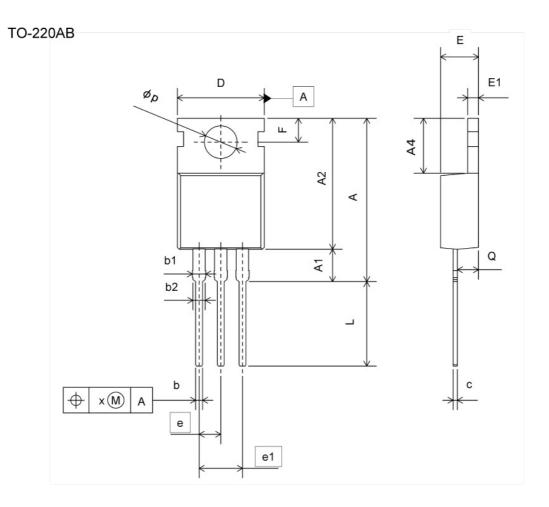


Fig.4-2 trr Waveform



Dimensions



| DIM | MILIME | TERS | INC | HES |
|----------|--------|-------|-------|-------|
| DIIVI | MIN | MAX | MIN | MAX |
| Α | 18.30 | 20.00 | 0.720 | 0.787 |
| A1 | 3.60 | 4.00 | 0.142 | 0.157 |
| A2 | 14.70 | 16.00 | 0.579 | 0.630 |
| A4 | 6.30 | 6.60 | 0.248 | 0.260 |
| b | 0.65 | 0.95 | 0.026 | 0.037 |
| b1 | 1.20 | 1.75 | 0.047 | 0.069 |
| b2 | 1.20 | 1.70 | 0.047 | 0.067 |
| С | 0.35 | 0.65 | 0.014 | 0.026 |
| D | 9.96 | 10.36 | 0.392 | 0.408 |
| E | 4.24 | 4.64 | 0.167 | 0.183 |
| E1 | 1.14 | 1.40 | 0.045 | 0.055 |
| е | 2. | 54 | 0.1 | 00 |
| e1 | 5. | 08 | 0.2 | 200 |
| F | 2.60 | 3.00 | 0.102 | 0.118 |
| L | 9.47 | 10.37 | 0.373 | 0.408 |
| ϕ p | 3.69 | 3.99 | 0.145 | 0.157 |
| Q | 2.30 | 2.70 | 0.091 | 0.106 |
| Х | -0 | 0.38 | - | 0.015 |

Dimension in mm/inches



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|---------|----------|------------|-----------|
| CLASSⅢ | CL ACCTI | CLASS II b | CL ACCIII |
| CLASSIV | CLASSⅢ | CLASSⅢ | CLASSⅢ |

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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